

INTERCONNECTS

SERIES 830, 831, 832, 833 • 2mm GRID HEADERS AND SOCKETS • SINGLE AND DOUBLE ROW STRIPS

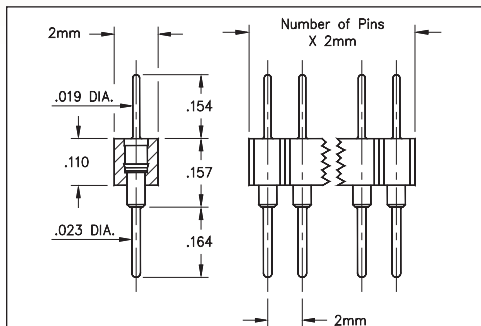


FIG. 1

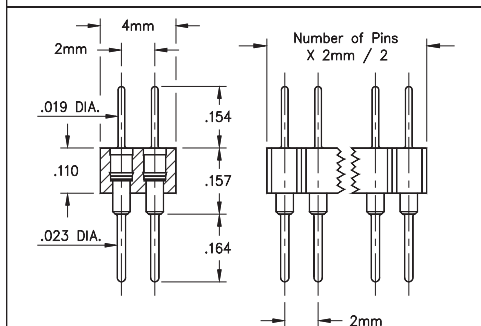


FIG. 2

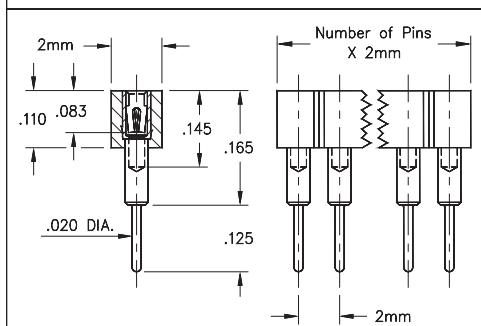


FIG. 3

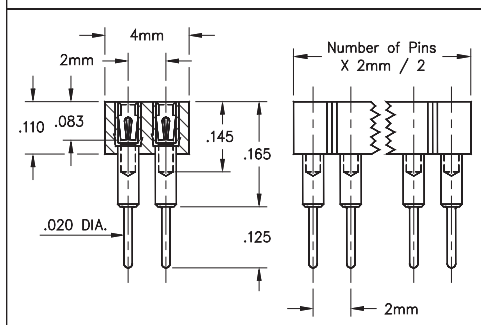
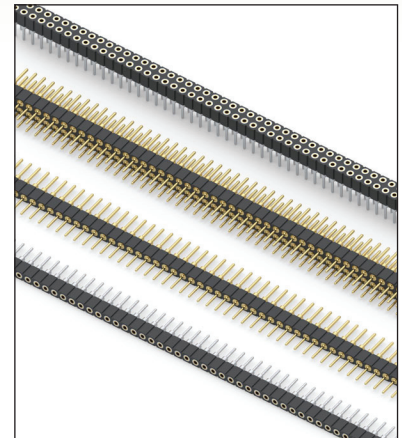


FIG. 4

- Series 830 single & double row interconnects have 2mm pin spacing and permit board stacking as low as .322"
- Pin headers (830 & 832 series) use MM #5012 pins. See page 208 for details
- Sockets (831 & 833 series) use MM #1802 receptacles and accept pin diameters from .015"-.025". See page 169 for details
- Contact is rated at 3 amps
- Insulators are high temperature thermoplastic, suitable for all soldering operations



ORDERING INFORMATION

FIG. 1	Series 830...001	Single Row Pin Header		
	830-XX-0-10-001000 Specify number of pins 01-50			
FIG. 2	Series 832...001	Double Row Pin Header		
	832-XX--10-001000 Specify number of pins 004-100			
RoHS-2 2011/65/EU XX=Plating Code See Below For Electrical, Mechanical & Environmental Data, See page 264				
SPECIFY PLATING CODE XX=		10 	90	40 
Pin Plating 		10 μ" Au	200 μ" Sn/Pb	200 μ" Sn

FIG. 3	Series 831...001		Single Row Socket				
	831-XX-0- -10-001000 Specify number of pins 01-50						
FIG. 4	Series 833...001		Double Row Socket				
	833-XX- - -10-001000 Specify number of pins 004-100						
RoHS-2 2011/65/EU XX=Plating Code See Below For Electrical, Mechanical & Environmental Data, See page 264							
SPECIFY PLATING CODE XX=							
Sleeve (Pin) 		91	93		41 	43 	47 
		200 μ" Sn/Pb	200 μ" Sn/Pb		200 μ" Sn	200 μ" Sn	200 μ" Sn
Contact (Clip) 		10 μ" Au	30 μ" Au		10 μ" Au	30 μ" Au	Au Flash